PCN Number:	20191209000.1A	PCN Date:	Jan. 15, 2020
Title:	Qualification of RFAB and TI Malaysia as additional Fab site and Assembly site options for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Mar 9, 2020	Estimated Sample Availability:	Date provided at sample request.

Change Type:					
☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☒	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Revision A is to correct the Assembly Site Origin (22L) reference in the Changes to product identification resulting from the PCN section.

This change notification is to announce the addition of RFAB and TI Malaysia as additional Fab site and Assembly site options for selected devices listed in the "Product Affected" section.

Fab Site:

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm

Assembly Site:

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
TI Mexico	MEX	MEX	Aguascalientes
TI Malaysia	**MLA**	**MYS**	**Kuala Lumpur**

There are no Material differences between sites. Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	**RFB**	**USA**	**Richardson**

Assembly Site

Current Assembly Site		
TI Mexico	Assembly Site Origin (22L)	ASO: MEX
TI Malaysia	Assembly Site Origin (22L)	~~ASO: QAB~~ **MLA**

Sample product shipping label (not actual product label)

Product Affected:

Group 1: Adding RFAB and TI Malaysia Assembly site		
SN65HVD182DDR	SN65LBC182DDR	THVD1500DR

Group 2: Adding RFAB only
THVD1500D

Qualification Report

Approve Date 23-Sep-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Type	Test Name / Condition	Duration	Qual Device: THVD1500D	QBS Process Reference: TPS51217DSC	QBS Package Reference: SN65HVD1781AQDRQ1
	AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
	CDM	ESD - CDM	1500 V	1/3/0	-	-
	ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-
	HAST	Biased HAST 130C/85%RH	96 Hours	-	3/231/0	3/231/0
	HBM	ESD - HBM	4000 V	1/3/0	-	-
	HBM	ESD - HBM	16000 V (Pins 6 and 7 Only)	1/3/0	-	-
	HTOL	Life Test, 125C	1000 Hours	-	-	2/154/0
	HTOL	Life Test, 135C	635 Hours	-	3/231/0	-
	HTOL	Life Test, 140C	480 Hours	-	-	1/77/0
	HTSL	High Temp Storage Bake 175C	500 Hours	-	-	1/45/0
	HTSL	High Temp Storage Bake, 170C	420 Hours	-	3/231/0	-
	LU	Latch-up	(Per JESD78)	1/6/0	-	-
	TC	Temperature Cycle -65/150C	500 Cycles	-	3/231/0	3/231/0
	WBP	Bond Pull	Wires	1/76/0	-	3/228/0
	WBS	Ball Bond Shear	Wires	1/76/0	-	3/228/0

- QBS: Qual By Similarity
- Qual Device THVD1500D is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com